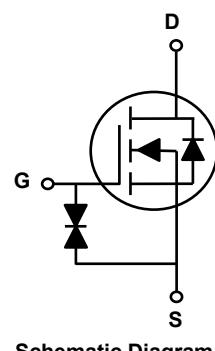
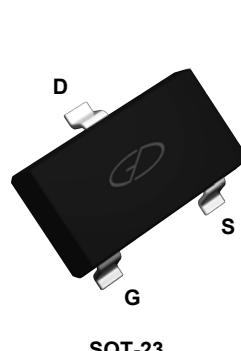


## Main Product Characteristics

BV <sub>DSS</sub>	20V
R <sub>DS(ON)</sub>	27mΩ
I <sub>D</sub>	6.5A



## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSF3416 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Drain Current-Continuous	I <sub>D</sub>	6.5	A
Drain Current-Pulsed <sup>1</sup>	I <sub>DM</sub>	30	A
Maximum Power Dissipation	P <sub>D</sub>	1.4	W
Thermal Resistance, Junction-to-Ambient <sup>2</sup>	R <sub>θJA</sub>	89	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 To +150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 To +150	°C

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
<b>On Characteristics<sup>3</sup></b>						
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6.5\text{A}$	-	17	27	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=5.5\text{A}$	-	21	33	
		$V_{\text{GS}}=1.8\text{V}, I_{\text{D}}=5\text{A}$	-	28	40	
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.45	0.7	1.0	V
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=6.5\text{A}$	8	-	-	S
<b>Dynamic and Switching Characteristics<sup>4</sup></b>						
Total Gate Charge	$Q_g$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=6.5\text{A}, V_{\text{GS}}=4.5\text{V}$	-	8	-	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		-	2.5	-	
Gate-Drain Charge	$Q_{\text{gd}}$		-	3	-	
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=10\text{V}, R_{\text{L}}=1.5\Omega$ $V_{\text{GS}}=5\text{V}, R_{\text{GEN}}=3\Omega$	-	0.5	-	$\text{nS}$
Turn-On Rise Time	$t_r$		-	1	-	
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	12	-	
Turn-Off Fall Time	$t_f$		-	4	-	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	660	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	160	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	87	-	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Current <sup>2</sup>	$I_s$		-	-	6.5	A
Diode Forward Voltage <sup>3</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_s=6.5\text{A}$	-	-	1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design

## Typical Electrical and Thermal Characteristic Curves

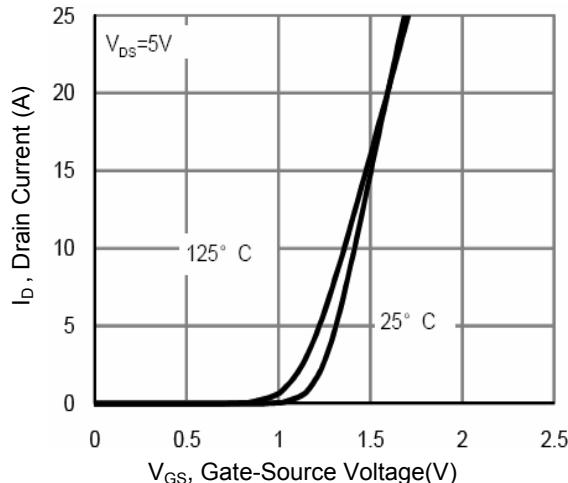


Figure 1. Transfer Characteristics

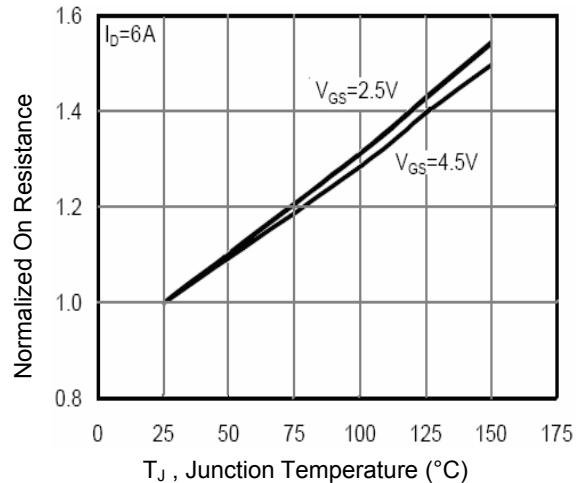


Figure 2. Rdson-Junction Temperature

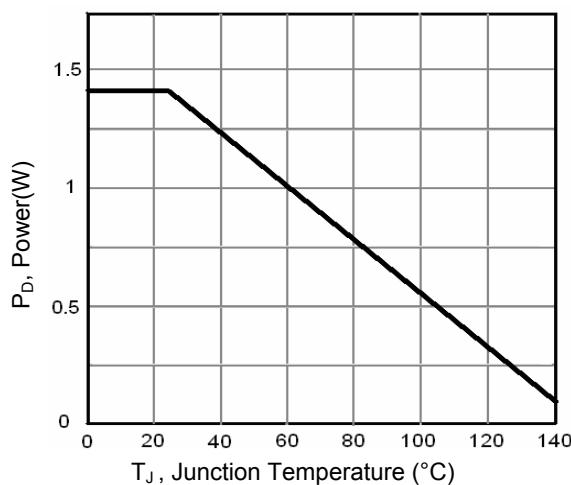


Figure 3. Power De-Rating

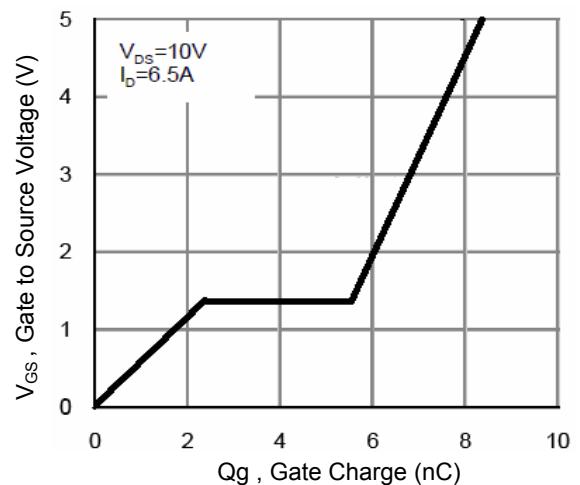


Figure 4. Gate Charge

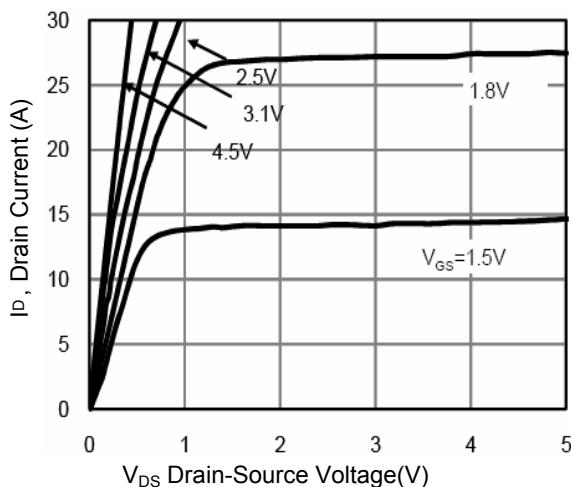


Figure 5. Output Characteristics

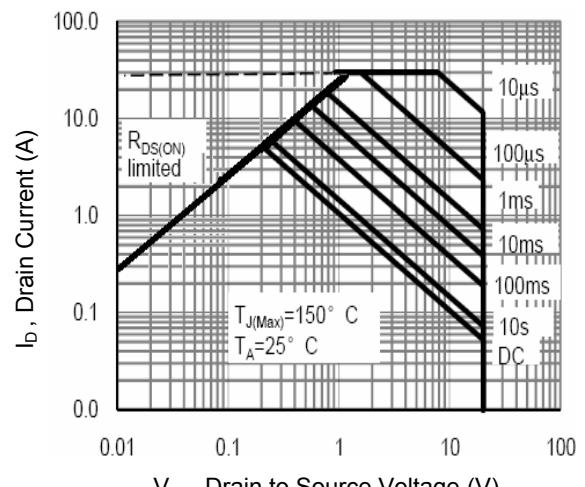


Figure 6. Safe Operation Area

### Typical Electrical and Thermal Characteristic Curves

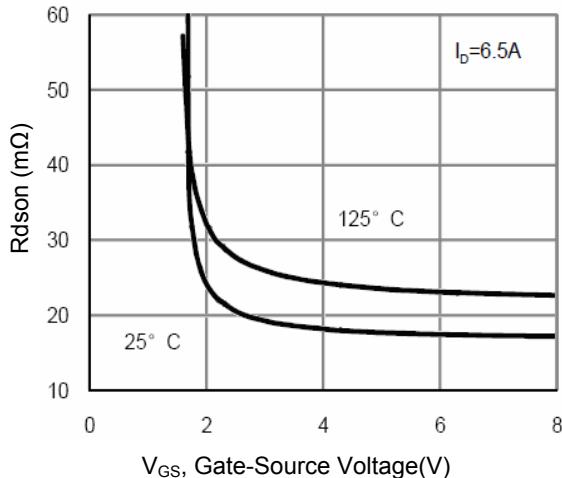


Figure 7.  $R_{dson}$  vs.  $V_{GS}$

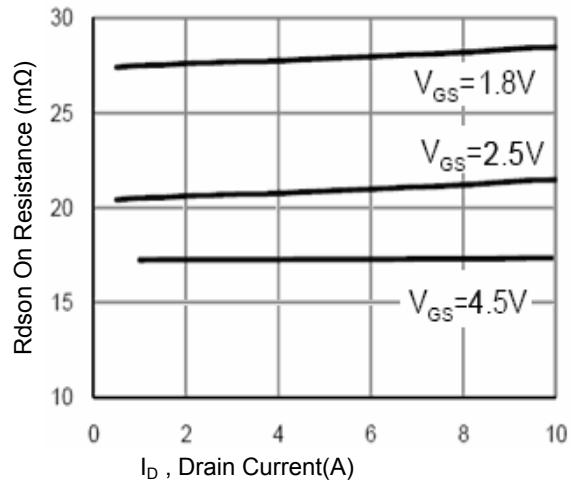


Figure 8.  $R_{dson}$ -Drain Current

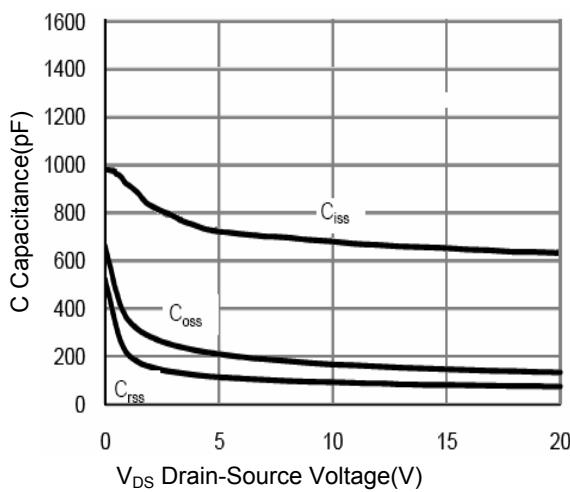


Figure 9. Capacitance vs.  $V_{DS}$

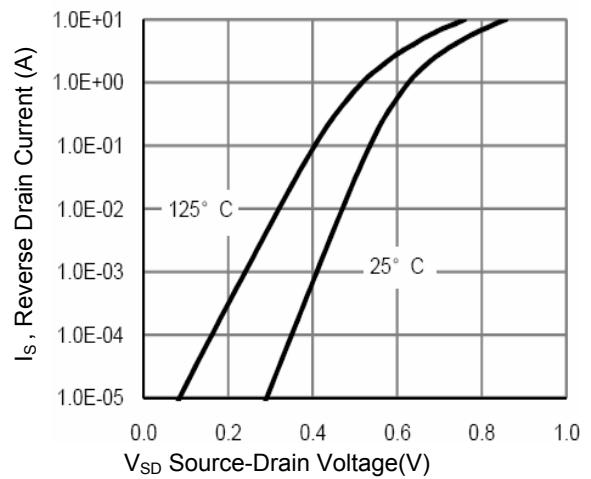


Figure 10. Source-Drain Diode Forward

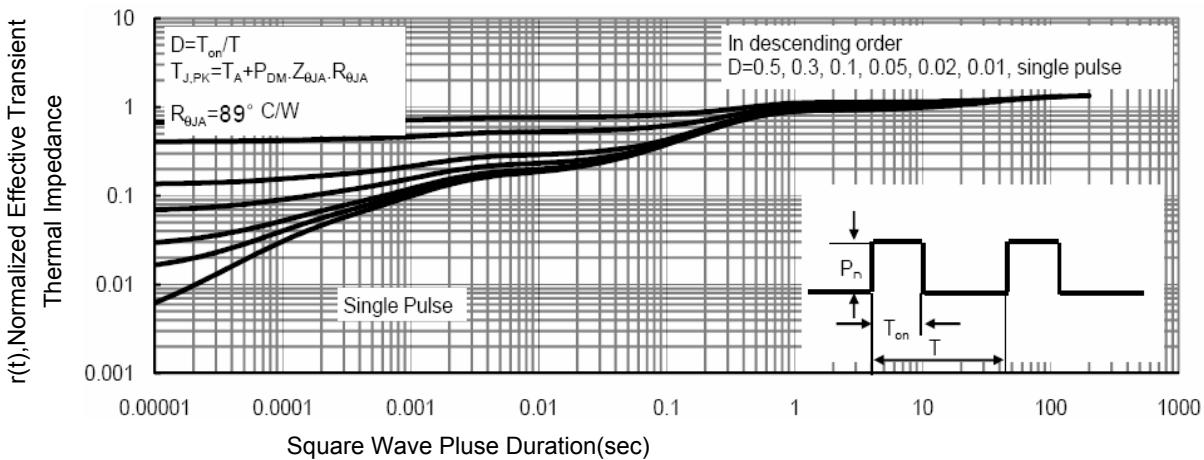


Figure 11. Normalized Maximum Transient Thermal Impedance

## Typical Electrical and Thermal Characteristic Curves

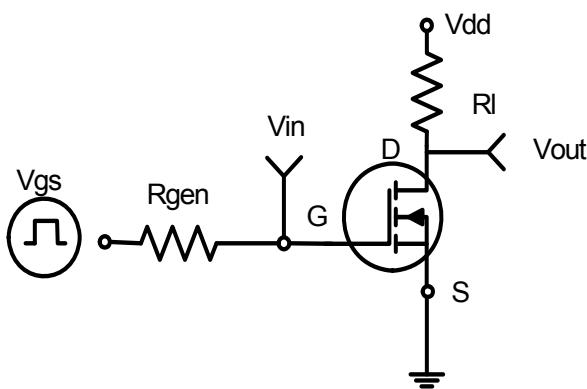


Figure 12. Switching Test Circuit

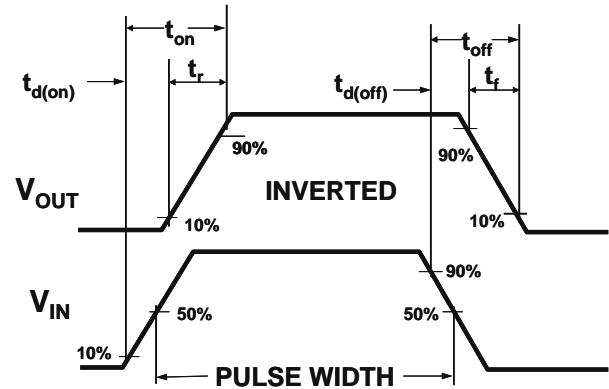
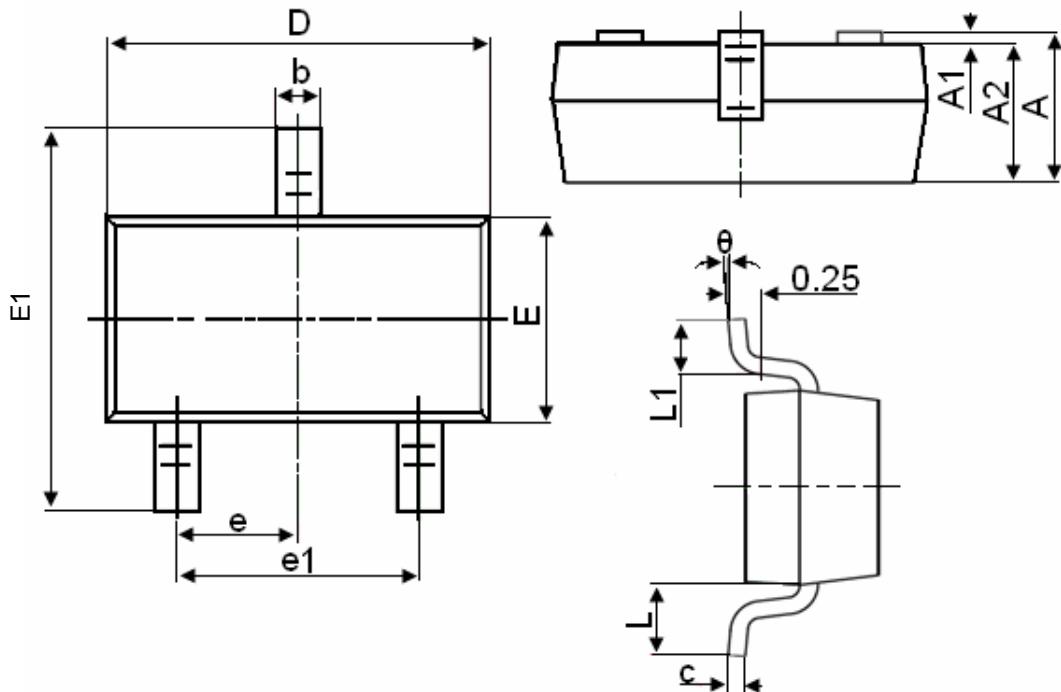


Figure 13. Switching Waveform

### Package Outline Dimensions (SOT-23)



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

#### Notes

1. All dimensions are in millimeters.
2. Tolerance  $\pm 0.10\text{mm}$  (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.